

| | | | | | | | |
|--|----|--|----------|--|--|---|-------------------------------|
| Form PTO 1449 (Modified) | | U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE | | ATTY DOCKET NO. 292873US41PCT | | SERIAL NO. 10/584,052 | |
| LIST OF REFERENCES CITED BY APPLICANT | | | | APPLICANT Stephane POCAS, et al. | | | |
| | | | | FILING DATE June 22, 2006 | | GROUP 2892 | |
| U.S. PATENT DOCUMENTS | | | | | | | |
| EXAMINER INITIAL | | DOCUMENT NUMBER | DATE | NAME | CLASS | SUB CLASS | FILING DATE IF APPROPRIATE |
| | AA | 6,340,812 | 01/22/02 | Yoshihiro IZUMI, et al | | | |
| | AB | 2004/0097008 A1 | 05/2004 | Glen J. LEEDY | | | |
| | AC | 5,374,564 | 12/20/94 | Michael BRUEL | | | |
| | AD | 6,281,039 | 08/28/01 | MARION | | | |
| | AF | 2004/0014299 | 01/22/04 | Hubert MORICEAU, et al. | | | |
| | AF | 5,880,010 | 03/1999 | Davison, HOWARD L. | | | |
| | AC | 6,097,096 | 08/2000 | GARDNER, et al. | | | |
| | AH | 6,465,892 | 10/2002 | SUGA, Tadatomo | | | |
| | AI | 6,809,008 | 10/2004 | HOLM, et al. | | | |
| | AJ | 6,809,358 | 10/2004 | HSIEH, et al. | | | |
| | AK | 6,902,987 | 06/2005 | TONG, et al. | | | |
| | AL | 7,452,745 | 11/2008 | DUPONT, et al. | | | |
| | AM | 2002/0164839 | 11/2002 | Paul M. ENQUIST | | | |
| | AN | 2002/0173118 | 11/2002 | DIETRICH, et al. | | | |
| FOREIGN PATENT DOCUMENTS | | | | | | | |
| | | DOCUMENT NUMBER | DATE | COUNTRY | TRANSLATION YES NO | | |
| | AO | 2 783 969 | 03/31/00 | France (equivalent of US 6, 281, 039) | | | X |
| | AP | 2 816 445 | 05/10/02 | France (equivalent of US 2004/0014299) | | | X |
| | AQ | WO/2003/028101 | 04/2003 | France (equivalent of US 2005/0020029) | | | X |
| | AR | WO/01/18853 A1 | 03/2001 | World Intellect (equivalent of US 7,208,392) | | | X |
| | AS | | | | | | |
| | AT | | | | | | |
| | AU | | | | | | |
| | AV | | | | | | |
| OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.) | | | | | | | |
| | AW | Q.-Y. TONG, et al., "SEMICONDUCTOR WAFER BONDING: SCIENCE AND TECHNOLOGY", JOHN WILEY & SONS, INC., XP 008042464, pages 215-219, 1999. | | | | | |
| | AX | Goran THUNGSTROM, et al., "CONTACTS TO MONOCRYSTALLINE N - AND P- TYPE CILLICON BY WAFER BONDING USING COBALT DISILICIDE", Physica Scripta, Vol. T54, 1994, pages 77-80. | | | | | |
| | AY | ISMAIL, M.S., et al., "PLATINUM SILICIDE FUSION BONDING", Electronics Letters, Vo. 27, No. 13, pages 1153-1155, 1991. | | | | | |
| | AZ | PLOESSL, A., et al., "WAFER DIRECT BONDING: TAILORING ADHESION BETWEEN BRITTLE MATERIALS", Materials Science and Engineering, Vol. 25, No. 1-2, pages 1-88, 1999. | | | | <input checked="" type="checkbox"/> Additional References sheet(s) attached | |
| Examiner | | | | | Date Considered | | |
| *Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. | | | | | | | |

| | | | | | | | |
|--|----|--|----------|-------------------------------------|--|--|-------------------------------|
| Form PTO 1449 (Modified) | | U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE | | ATTY DOCKET NO. 292873US41PCT | | SERIAL NO. 10/584,052 | |
| LIST OF REFERENCES CITED BY APPLICANT | | | | APPLICANT Stephane POCAS, et al. | | | |
| | | | | FILING DATE June 22, 2006 | | GROUP 2892 | |
| U.S. PATENT DOCUMENTS | | | | | | | |
| EXAMINER INITIAL | | DOCUMENT NUMBER | DATE | NAME | CLASS | SUB CLASS | FILING DATE IF APPROPRIATE |
| | BA | 2003/0129780 | 07/2003 | Andre AUBERTON-HERVE | | | |
| | BB | 2005/0020029 | 01/2005 | JEAN-SEBASTIEN, Danel | | | |
| | BC | 2005/0104089 | 05/2005 | ENGELMANN, et al. | | | |
| | BD | 7,208,392 B1 | 04/2007 | JAUSSAUD, et al. | | | |
| | BE | 6,242,324 B1 | 06/2001 | KUB, et al. | | | |
| | BF | 2008/0041517 | 02/21/08 | Hubert MORICEAU, et al. | | | |
| | BG | 2008/0296712 | 12/04/08 | Guy FEUILLET, et al. | | | |
| | BH | | | | | | |
| | BI | | | | | | |
| | BJ | | | | | | |
| | BK | | | | | | |
| | BL | | | | | | |
| | BM | | | | | | |
| | BN | | | | | | |
| FOREIGN PATENT DOCUMENTS | | | | | | | |
| | | DOCUMENT NUMBER | DATE | COUNTRY | TRANSLATION YES NO | | |
| | BO | | | | | | |
| | BP | | | | | | |
| | BO | | | | | | |
| | BP | | | | | | |
| | BS | | | | | | |
| | BT | | | | | | |
| | BU | | | | | | |
| | BV | | | | | | |
| OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.) | | | | | | | |
| | BW | SHIGETOU, A., et al., "ROOM TEMPERATURE BONDING OF ULTRA-FINE PITCH AND LOW-PROFILED CU ELECTRODES FOR BUMP-LESS INTERCONNECT", Electronic Components and Technology Conference, Vol. 53, pages 848-852, 2003. | | | | | |
| | BX | LJUNGBERG, K., et al., "BURIED COBALT SILICIDE LAYERS IN SILICON CREATED BY WAFER BONDING", Journal of the Electrochemical Society, Vol. 141, No. 10, pages 2829-2833, 1994. | | | | | |
| | BY | B. ASPAR, et al., "SMART-CUT PROCESS USING METALLIC BONDING: APPLICATION TO TRANSFER OF Si, GaAs, InP THIN FILMS", Electronics Letters, Vol. 35, No. 12, June 10, 1999, pages 1024-1025. | | | | | |
| | BZ | | | | | <input type="checkbox"/> Additional References sheet(s) attached | |
| Examiner | | | | | Date Considered | | |
| *Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. | | | | | | | |